

2-PART SILICONE GAP FILLER TDG-L-SI-2C-Y HALA

dispensable / 2 parts / Low Volatile Siloxanes (LV) / Form-in-Place

TDG-L-SI-2C-Y is a 2-part dispensable low volatile LV silicone gap filler which is filled with thermally conductive fillers. After curing under heat the system remains elastic. It is characterised by very good dielectric and mechanic properties and is suited for compensating extreme tolerances and spaces at non-coplanar systems. Its thixotropic behaviour allows for a definite placement and cure-in-place. It has a natural low level tack that enhances a good thermal contact. Due to its negligible and controlled volatile content it is suited for environments where volatile silicones and paint wetting impairment are critical.



Release 09 / 2025

PROPERTIES

- ☐ Dispensable 2-part silicone
- ☐ Low volatile siloxane content (LV)
- ☐ No paint wetting impairment
- ☐ Thermal conductivity: 2.0 W/mK
- ☐ Remains elastic after polymerisation
- ☐ Zero stress on components
- ☐ Heat accelerated curing
- ☐ Shock absorbing

AVAILABILITY

- ☐ Cartridges 2 x 25 ml / 2 x 100 ml / 2 x 200 ml / 2 x 600 ml
- ☐ Pail 2 x 25 kg / 2 x 35 kg
- ☐ On request

APPLICATION EXAMPLES

Thermal link of:

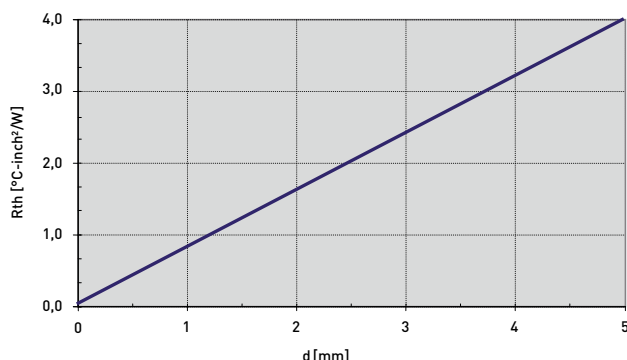
- ☐ FPBGA
- ☐ Capacitors
- ☐ Heat Pipes
- ☐ BGA

For use in Automotive applications
/ Telecommunication / Multimedia / Industrial PCs

Technical Data Sheet

PROPERTY	UNIT	A Part	B Part
MATERIAL			
Colour		Yellow	White
Density @ 25 °C	g/cm ³	1.9	1.9
Mixing Ratio	Weight or Volume	1 : 1	1 : 1
Hardness	Shore 00	52	52
Viscosity [Brookfield @ 10 rpm, 25 °C]	Pas	260	260
Viscosity (mixed) [Brookfield @ 10 rpm, 25 °C]	Pas	260	260
Pot Life @ 25 °C and 65 % RH (Time for viscosity to double)	min	> 120	> 120
Curing Time @ 25 °C / 100 °C		< 24h / 15 - 30 min	< 24h / 15 - 30 min
Shelf Life (from Date of Manufacturing, unopened, @ < 35 °C)	Months	6	6
Outgasing ¹	TML / CVCM / WVR %	0.16 / 0.03 / 0.04	0.16 / 0.03 / 0.04
No Paint Wetting Impairment Substances (PWIS) ²		Passed	Passed
Flammability	UL 94	VO	VO
RoHS Conformity	2015 / 863 / EU	Yes	Yes
TECHNICAL			
Thermal Conductivity ³	W/mK	2.0	2.0
Operating Temperature	°C	- 50 to + 150	- 50 to + 150
Dielectric Strength	kV/mm	> 10	> 10
Volume Resistivity	Ohm - cm	1 x 10 ¹⁰	1 x 10 ¹⁰

Measurement technique according to: ¹ ASTM E 595, ² P-VW 3-10.7 57650 Temp. Test, ³ ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.
Warning: Only A / B part of the same lot number may be processed together.



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